IPC ASSOCIATION CONNECTELECTRONICS INDUSTRI	Material Composi © Copyright 2005. IPC, international and Pan-Ar	Bannockb	urn, Illinois. A	Il rights reserved untions.	der both	Γhis docume evel parts, t	ent is a declar he declaration	ation of t n encomp	he substance asses all low	s within the manufacturer level materials for v	rer listed which the	item. Note: it manufacturer	f the item is an as has engineering	ssembly with low responsibility.	
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Form Type Distribute				:	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia					als and Mfg Information			
upplier Infor	rmation														
Company name*		Company unique ID				Unique ID Authority				Respon	Response Date*				
nsemi											2023-0	2023-06-07			
Contact Name		Title - Contact				Phone - Contact*				Email	Email - Contact*				
Product-Env-Ste	wards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	esentative*	Title - Representative			Phone - Representative*				Email	Email - Representative*					
Product-Env-Ste	wards	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Reque	ester Item Number	n Number Mfr Item Name				Effective Da	te Vers	sion	Manufacturing Site		Weight*	UOM	Unit Type		
		G Regulat		Ultra-Low IQ 150 mA CMOS LDO Regulator, Act Discharge, Vout=2.8V, automotive		2023-06-07			CN1		2.79	mg	Each		
Ianufacturin	g Proccess Information	n													
Terminal Plating / Grid Array Material Termin			erminal Base Alloy J-STD-020 MSL Rating			Rating	Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy			1			260		С	30	seco	nds 3				
omments															
vel 1 - maximun	n time at peak temperature o	during sol	dering is 10-3	0 seconds											
or more informa	ation regarding material con	nposition]	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.12	mg	Supplier	Silicon (Si)	7440-21-3		0.12	mg
Lead Frame	1.18	mg	В	Nickel (Ni)	7440-02-0		0.4283	mg
			Supplier	Iron (Fe)	7439-89-6		0.5924	mg
			Supplier	Copper (Cu)	7440-50-8		0.1593	mg
Mold Compound-Black	1.4	mg		Epoxy Phenol Resin	proprietary data		0.147	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.253	mg
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg